

Atty. Docket No. YOR920080081US1

RECORDATION FORM COVER SHEET PATENTS ONLY

To The Honorable Commissioner of Patents and Trademarks:
Please record the attached original documents or copy thereof.

<p>1. Name of conveying party(ies):</p> <p>Dae-Gyu Park Michael P. Chudzik Vijay Narayanan Vamsi Paruchuri</p> <p>Additional name(s) of conveying party(ies) attached? <u> </u> Yes <u> X </u> No</p>	<p>2. Name and address of receiving party(ies):</p> <p>Name: <u>International Business Machines Corporation</u> Address: <u>New Orchard Road</u> <u>Armonk, NY 10504</u></p> <p>Additional name(s) & addresses attached? <u> </u> Yes <u> X </u> No</p>
<p>3. Nature of conveyance:</p> <p><u> X </u> Assignment</p> <p>Execution Date(s): <u>05/14/2008,</u> <u>05/14/2008, 05/14/2008, and 05/14/2008.</u></p>	<p>4. Patent Application number(s)</p> <p align="center"><u>12/120,658</u></p> <p>Execution Date(s): <u>05/14/2008,</u> <u>05/14/2008, 05/14/2008, and 05/14/2008.</u></p>
<p>5. Name and address of party to whom correspondence concerning document should be mailed:</p> <p>Name: <u>George Sai-HalasZ</u> Gddress: <u>303 Taber Avenue</u> <u>Providence, RI 02906</u></p>	<p>6. Total number of applications involved: <u>1</u></p> <p>7. Total fee (37 CFR 3.41): <u>\$40.00</u></p> <p><u> X </u> Charge to Deposit Account No.: <u>50-0510</u></p>

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8. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of original document.

George Sai-HalasZ (Reg. No. 45,430) *George Sai-HalasZ* 06/19/2008
Name of Person Signing Signature Date

Total Number of pages including cover sheet, attachments, and document: 5

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CH \$40.00 500510 12120658

(JOINT FORM)
(FOUR INVENTORS)

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Assignment

Whereas, we

INVENTOR AND CITY	(1) Dae-Gyu Park County of Dutchess	of Poughquag and State of New York
INVENTOR AND CITY	(2) Michael P. Chudzik County of Fairfield	of Danbury and State of Connecticut
INVENTOR AND CITY	(3) Vijay Narayanan County of Manhattan	of New York and State of New York
INVENTOR AND CITY	(4) Vamsi Paruchuri County of Manhattan	of New York and State of New York

have invented certain improvements in

TITLE **Fabrication of self-aligned CMOS structure**

DATES THAT
INVENTORS
SIGNED THE
DECLARATION

and executed, respectively, a United States nonprovisional patent application therefor on (1) 05/14/2008 and (2) 05/14/2008 and (3) 05/14/2008 and (4) 05/14/2008.

Whereas, INTERNATIONAL BUSINESS MACHINES CORPORATION, a corporation of New York, having a place of business at Armonk, New York 10504, (hereinafter called IBM), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefor;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, we, the above named, hereby sell, assign, and transfer to IBM, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and in all foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said applications to IBM, its successors and assigns; and we hereby agree that IBM may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by IBM.

(JOINT FORM)
(FOUR INVENTORS)

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Assignment

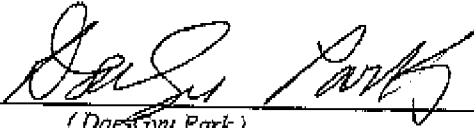
Fabrication of self-aligned CMOS structure

Signed and sealed

CITY AND
DATE

(1) at
on

Fishkill NY
5/14/08



(Dae-Gyu Park)
FIRST NAME MIDDLE INITIAL LAST NAME
SIGNATURE
INVENTOR

Signed and sealed

CITY AND
DATE

(2) at
on

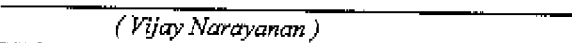
Fishkill NY
5/14/08


(Michael P. Chudzik)
FIRST NAME MIDDLE INITIAL LAST NAME
SIGNATURE
INVENTOR

Signed and sealed

CITY AND
DATE

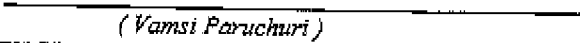
(3) at
on


(Vijay Narayanan)
FIRST NAME MIDDLE INITIAL LAST NAME
SIGNATURE
INVENTOR

Signed and sealed

CITY AND
DATE

(4) at
on


(Vamsi Paruchuri)
FIRST NAME MIDDLE INITIAL LAST NAME
SIGNATURE
INVENTOR

(JOINT FORM)
(FOUR INVENTORS)

Docket YOR920080081US1, Page 2 of 2

Assignment

Fabrication of self-aligned CMOS structure

Signed and sealed

CITY AND
DATE

(1) at
on

(Dae-Gyu Park)
FIRST NAME MIDDLE INITIAL LAST NAME

SIGNATURE
INVENTOR

Signed and sealed

CITY AND
DATE

(2) at
on

(Michael P. Chudzik)
FIRST NAME MIDDLE INITIAL LAST NAME

SIGNATURE
INVENTOR

Signed and sealed

CITY AND
DATE

(3) at Yorktown Heights, NY
on 05/14/08

(Vijay Narayanan)
FIRST NAME MIDDLE INITIAL LAST NAME

SIGNATURE
INVENTOR

Signed and sealed

CITY AND
DATE

(4) at
on

(Vamsi Paruchuri)
FIRST NAME MIDDLE INITIAL LAST NAME

SIGNATURE
INVENTOR

(JOINT FORM)
(FOUR INVENTORS)

Docket YOR920080081US1, Page 2 of 2

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(1) at
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INVENTOR

Signed and sealed

CITY AND
DATE

(2) at
on

(Michael P. Chudzik)
FIRST NAME MIDDLE INITIAL LAST NAME
SIGNATURE
INVENTOR

Signed and sealed

CITY AND
DATE

(3) at
on

(Vijay Narayanan)
FIRST NAME MIDDLE INITIAL LAST NAME
SIGNATURE
INVENTOR

Signed and sealed

CITY AND
DATE

(4) at Albany, NY
on 05/14/08

P. Vamsi Krishna
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FIRST NAME MIDDLE INITIAL LAST NAME
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INVENTOR